

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

74F620 • 74F623 Inverting Octal Bus Transceiver with 3-STATE Outputs

General Description

These devices are octal bus transceivers designed for asynchronous two-way data flow between the A and B buses. Both busses are capable of sinking 64 mA and have 3-STATE outputs. Dual enable pins (GAB, $\bar{G}BA$) allow data transmission from the A bus to the B bus or from the B bus to the A bus. The 74F620 is an inverting option of the 74F623.

Features

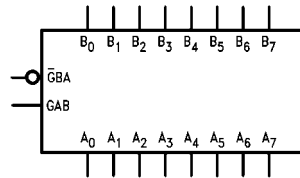
- Designed for asynchronous two-way data flow between busses
- Outputs sink 64 mA
- Dual enable inputs control direction of data flow
- Guaranteed 4000V minimum ESD protection
- 74F620 is an inverting option of the 74F623

Ordering Code:

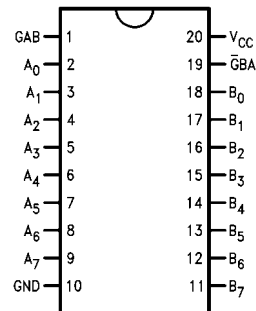
Order Number	Package Number	Package Description
74F620PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
74F623SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F623PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$\overline{G}BA, GAB$	Enable Inputs	1.0/1.0	20 μA / -0.6 mA
A_0-A_7	A Inputs or 3-STATE Outputs	3.5/1.083	70 μA / -0.4 mA
B_0-B_7	B Inputs or 3-STATE Outputs	3.5/1.083	70 μA / -0.4 mA

Functional Description

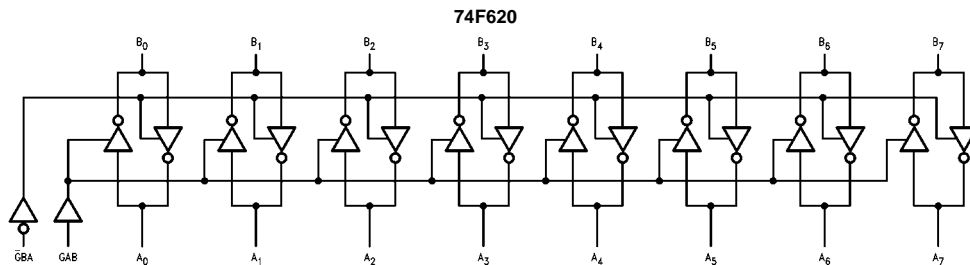
The enable inputs GAB and $\overline{G}BA$ control whether data is transmitted from the A bus to the B bus or from the B bus to the A bus. If both $\overline{G}BA$ and GAB are disabled ($\overline{G}BA$ HIGH and GAB LOW), the outputs are in the high impedance state and data is stored at the A and B busses. When $\overline{G}BA$ is active LOW, B data is sent to the A bus. When GAB is active HIGH, data from the A bus is sent to the B bus. If both enable inputs are active ($\overline{G}BA$ LOW and GAB HIGH) B data is sent to the A bus while A data is sent to the B bus.

Function Table

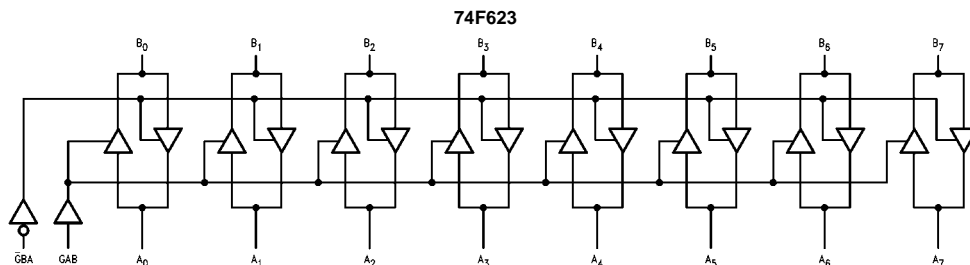
Enable Inputs		Operation	
$\overline{G}BA$	GAB	74F620	74F623
L	L	\overline{B} Data to A Bus	B Data to A Bus
H	H	\overline{A} Data to B Bus	A Data to B Bus
H	L	Z	Z
L	H	\overline{B} Data to A Bus, \overline{A} Data to B Bus	B Data to A Bus, A Data to B Bus

H = HIGH Voltage Level
L = LOW Voltage Level
Z = High Impedance

Logic Diagrams



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.



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Absolute Maximum Ratings(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	-0.5V to V _{CC}
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

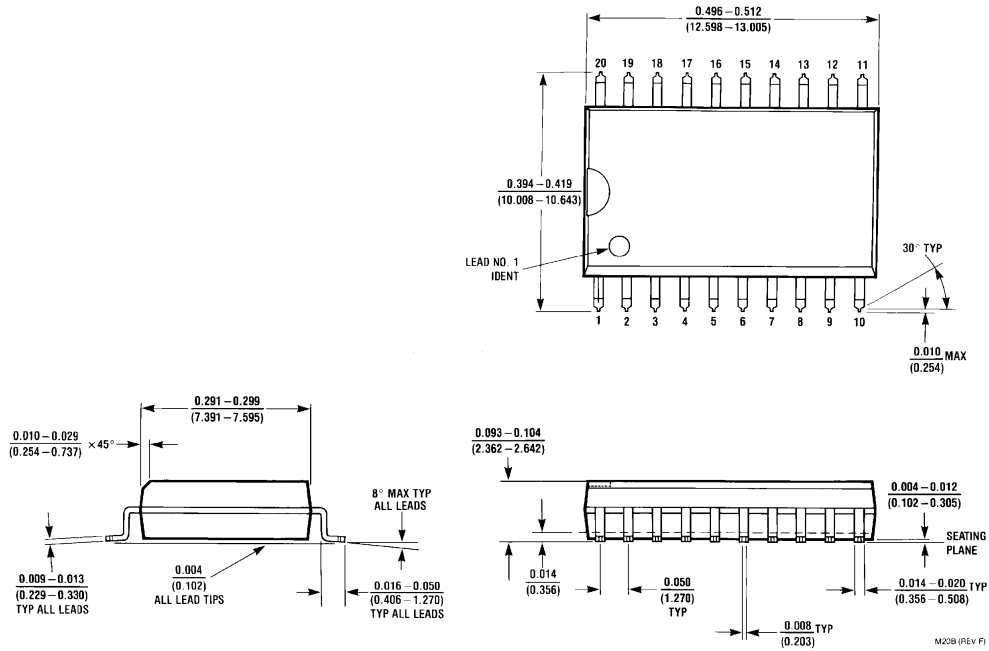
Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

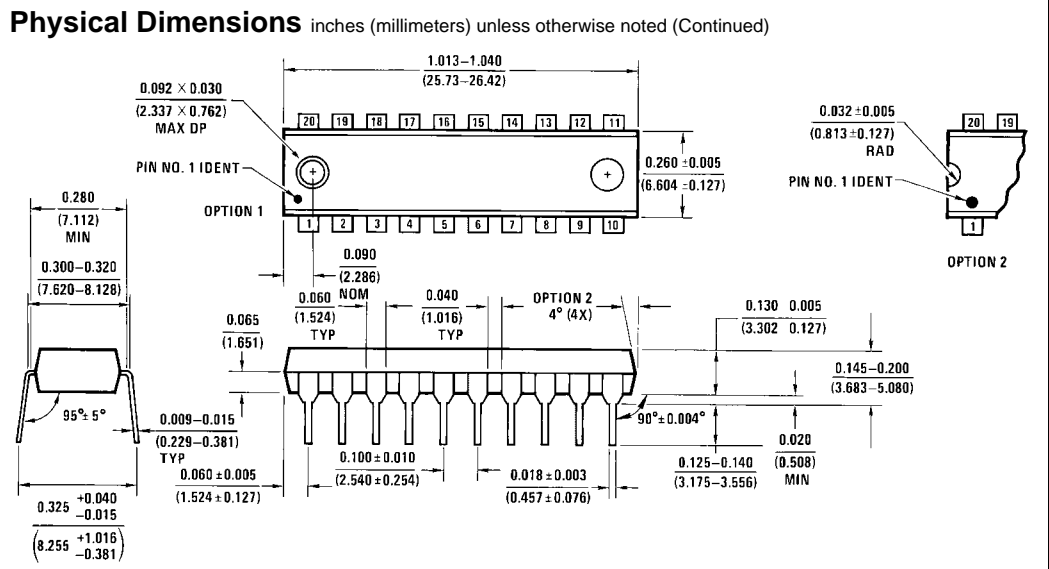
Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA (Non I/O Pins)
V _{OH}	Output HIGH Voltage 10% V _{CC}	2.0			V	Min	I _{OH} = -15 mA (A _n , B _n)
V _{OL}	Output LOW Voltage 10% V _{CC}			0.55	V	Min	I _{OL} = 64 mA (A _n , B _n)
I _{IH}	Input HIGH Current			5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V (GBA, GAB)
I _{BVIT}	Input HIGH Current Breakdown (I/O)			0.5	mA	Max	V _{IN} = 5.5V (A _n , B _n)
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V (Non I/O Pins)
I _{IH} + I _{OZH}	Output Leakage Current			70	μA	Max	V _{OUT} = 2.7V (A _n , B _n)
I _{IL} + I _{OZL}	Output Leakage Current			-650	μA	Max	V _{OUT} = 0.5V (A _n , B _n)
I _{OS}	Output Short-Circuit Current	-100		-225	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μA	0.0V	V _{OUT} = 5.25V
I _{CCH}	Power Supply Current (74F620)			82	mA	Max	V _O = HIGH, V _{IN} = 0.2V
I _{CCL}	Power Supply Current (74F620)			82	mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current (74F620)			95	mA	Max	V _O = HIGH Z
I _{CCH}	Power Supply Current (74F623)			65	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current (74F623)			82	mA	Max	V _O = LOW, V _{IN} = 0.2V
I _{CCZ}	Power Supply Current (74F623)			85	mA	Max	V _O = HIGH Z

AC Electrical Characteristics							
Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay	2.5		7.5	2.0	8.0	ns
t _{PHL}	A Input to B Output (74F620)	2.0		7.0	2.0	7.0	
t _{PLH}	Propagation Delay	2.5		7.5	2.0	8.0	ns
t _{PHL}	B Input to A Output (74F620)	2.0		7.0	2.0	7.0	
t _{PLH}	Propagation Delay	1.5		6.5	1.5	7.5	ns
t _{PHL}	A Input to B Output (74F623)	2.0		7.0	2.0	7.5	
t _{PLH}	Propagation Delay	1.5		6.5	1.5	7.5	ns
t _{PHL}	B Input to A Output (74F623)	2.0		7.0	2.0	7.5	
t _{PZH}	Enable Time	2.0		7.0	2.0	8.0	ns
t _{PZL}	GBA Input to A Output	2.5		8.0	2.0	8.5	
t _{PHZ}	Disable Time	1.5		6.5	1.5	7.5	
t _{PLZ}	GBA Input to A Output	1.0		5.5	1.0	5.5	
t _{PZH}	Enable Time	2.0		7.5	2.0	8.5	ns
t _{PZL}	GAB Input to B Output (74F620)	3.0		8.0	2.0	8.5	
t _{PHZ}	Disable Time	2.5		8.0	2.0	9.0	
t _{PLZ}	GAB Input to B Output (74F620)	2.0		7.5	2.0	8.0	
t _{PZH}	Enable Time	2.0		7.5	2.0	8.5	ns
t _{PZL}	GAB Input to B Output (74F623)	2.5		8.0	2.0	8.5	
t _{PHZ}	Disable Time	2.0		8.0	2.0	9.0	
t _{PLZ}	GAB Input to B Output (74F623)	2.0		8.0	2.0	8.0	

Physical Dimensions inches (millimeters) unless otherwise noted



**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B**



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N20A

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